

# EPIGAP Optronic GmbH

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## Product Data Sheet

### LED Chip Infra Red

### EOLC-870-17-2

Rev. 01 aus 2011

Radiation	Type	Electrodes
Infra Red	DDH	P (anode) up

	<b>typ. Dimensions (μm)</b>	
	typ. Thickness:	160 (±20) μm
	anode:	gold alloy, 1.5 μm
	cathode:	gold alloy, 0.5 μm structured, 25% covered

### Optical and Electrical Characteristics

T<sub>amb</sub> = 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	I <sub>F</sub> =20mA	V <sub>F</sub>		1.4	1.6	V
Reverse voltage	I <sub>R</sub> =100μA	V <sub>R</sub>	5			V
Radiant power <sup>1</sup>	I <sub>F</sub> =20mA	Φ <sub>e</sub>	4.0	6.0		mW
Radiant power <sup>2</sup>	I <sub>F</sub> =20mA	Φ <sub>e</sub>		11.0		mW
Peak wavelength	I <sub>F</sub> =20mA	λ <sub>p</sub>	855	870	880	nm
Spectral bandwidth at 50%	I <sub>F</sub> =20mA	Δλ <sub>0,5</sub>		45		nm
Switching time	I <sub>F</sub> =20mA	t <sub>r</sub> , t <sub>f</sub>		10/20		ns

<sup>1</sup> Measured on bare chip on TO18 header

<sup>2</sup> Measured on epoxy covered chip on TO18 header

### Labeling

Type	Lot N°	Φ <sub>e</sub> (typ) [mW]	V <sub>F</sub> (typ) [V]	Quantity
EOLC-870-17-2				

### Packing

Chips on adhesive film with wire-bond side top